



PRODUCT APPROVAL SHEET

Product Type	XUA-49U Quartz Crystal
CREC's P/N	01.X.UA.130JMVE0001843200
Description	X'Tal XUA-49U 1.843200MHz 30pF ±20ppm 500ohm 2 Lead
Customer Number	LBY001
Customer P/N	-
Customer Name	-
Veision	B0
Spec No.	LBY001XUA001

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Assembly				
Test				
Web Site	www.chinacrec.com			



PRODUCT SPECIFICATION

XUA-49U Quartz Crystal



【 CONTENTS 】

1 Part explanation	3
2 SCOPE	3
3 Reference Standard	3
4 Title Guide	3
5 Performance.....	4
6 Figure.....	4
6.1 Product Dimensions	4
6.2 Marking	6
7 Packing specification	6
7.1 Self-sealing plastic bag and Inner Box.....	6
7.2 Carton Dimensions and Q'ty	6
8 Reliability Test Item	6
9 Product handling and control procedure.....	7
9.1 Precautions for storage.....	7
9.2 Mounting of SMD TYPE products.....	7
9.3 Ultrasonic cleaning.....	7
9.4 Ultrasonic welding.....	7

Rev	CREC's P/N	Cust P/N	Page
B0	01.X.UA.130JMVE0001843200	-	2

1 Parts explanation

This part is a miniature AT cut stirp crystal units with 49U Qua miniature BASE. It is mainly used in mobile , wifi, bluetooth and telecommunications application.

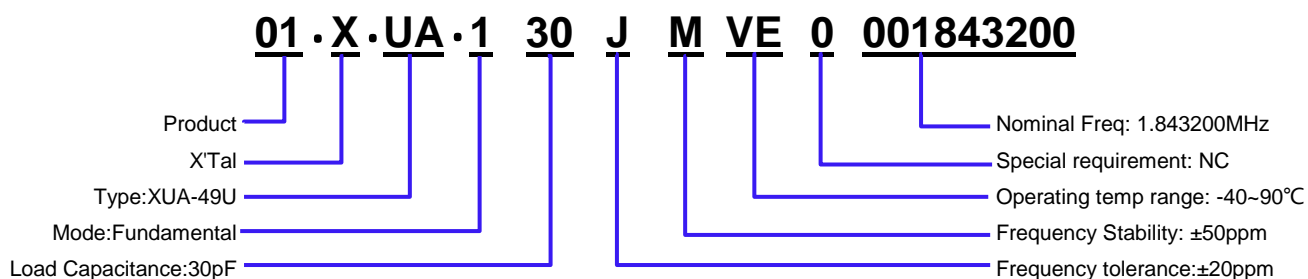
2 SCOPE

This specification only covers CREC's 01.X.UA.130JMVE0001843200

3 Reference Standard

- 3.1 MIL-STD-883H :Environmental tests' Mechanical tests.
- 3.2 MIL-STD-202 : Test Methods for Electronic and Electrical component part.
- 3.3 IEC 60068-2 :Environmental tests' Mechanical tests.
- 3.4 ANSI/EIA-481-C : 8mm through 200mm enbossed carrier taping and 24mm punched
- 3.5 JEDEC J-STD-020C: Soldering

4 Title Guide



Rev	CREC's P/N	Cust P/N	Page
B0	01.X.UA.130JMVE0001843200	-	3

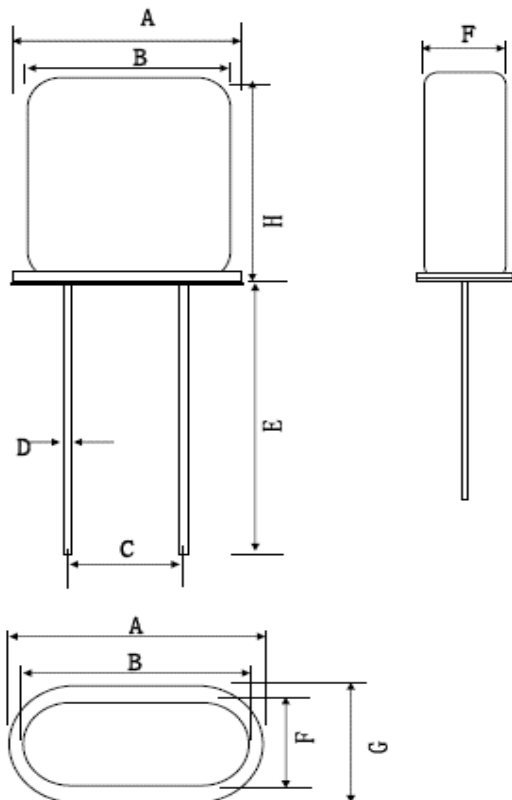
5 Performance

Electrical Performance. Electrical characteristics measured by S&A250B.

No.	Item	Symb.	Electrical Specification				Remark (Humidity: 40%~60%)
			Min.	Type	Max.	Unit	
1	Nominal Frequency	F0	1.843200			MHz	-
2	Mode of vibration	-	Fundamental			-	-
3	Frequency tolerance	$\Delta F/F0$	-20	-	20	ppm	25°C±3°C
4	Operating Temperature Range	T _{OPR}	-40	-	90	°C	-
5	Frequency Stability	T _C	-50	-	50	ppm	-40~90°C
6	Storage Temperature	T _{stg}	-55	-	125	°C	-
7	Load Capacitance	CL	-	30	-	pF	-
8	Equivalent Series Resistance	ESR	-	-	500	Ω	25°C±3°C
9	Drive Level	DL	-	-	100	μW	-
10	Insulation Resistance	IR	500	-	-	Mohm	@DC100V
11	Shunt Capacitance	C0	-	-	7	pF	25°C±3°C
12	Motional Capacitance	C1	-	-	-	fF	25°C±3°C
13	Trim Sensivity	T _s	-	-	-	ppm/pF	25°C±3°C
14	Spurious	SPDB	-	-	-3	dB	±5000ppm
15	Aging	Aging	-3	-	3	ppm	First Year
16	DLD2		-	-	150	Ω	0.1~100uW 10
17	FDDL		-5	-	5	ppm	0.1~100uW 10

6 Figure

6.1 Product Dimensions (Unit:mm)



A	11.50MAX
B	10.30MAX
C	4.88±0.2
D	0.45±0.05
E	13.2±1
F	3.80MAX
G	4.70MAX
H	13.6MAX

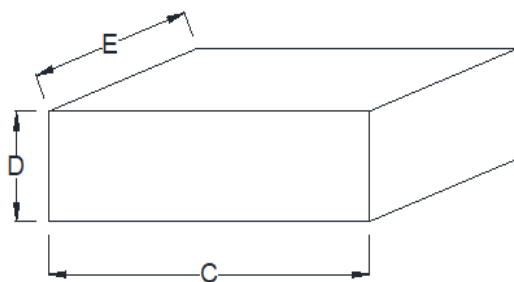
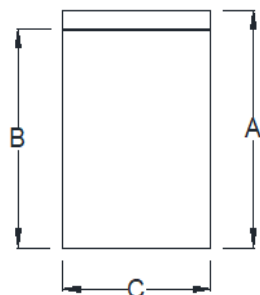
Rev	CREC's P/N	Cust P/N	Page
B0	01.X.UA.130JMVE0001843200	-	4

6.2 Marking



7 Packing specification

7.1 Self-sealing plastic bag and Inner Box

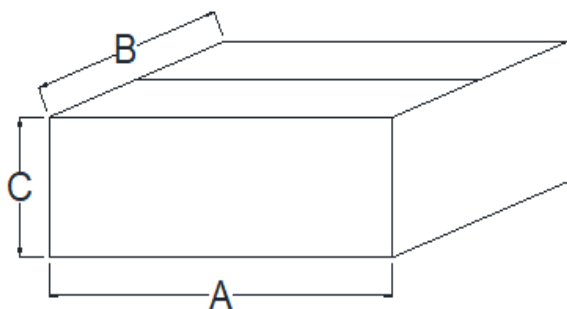


Self-sealing plastic bag

Inner Box

Item	Self-sealing plastic bag			Inner Box		
	A	B	C	D	E	F
Spec(mm)	125	115	84	184	184	126
Tol.(mm)	±0.50	±0.50	±0.50	-	-	-
Q'ty (pcs)	100/Bag Max			1K/Box Max		

7.2 Carton



Item	A	B	C
SPEC(mm)	410	350	150
Q'ty (pcs)	10K/Carton Max		

Rev	CREC's P/N	Cust P/N	Page
B0	01.X.UA.130JMVE0001843200	-	5

8 Reliability Test Item

No.	Item	Test Condition	Reference
1	Drop Test	Height: 50cm Times: 2 times on hardWood	IEC68-2-32 Free Fall
2	Vibration	Frequency: 20 to2000Hz, full wave Amplitude: 1.5 mm (Peak to Peak) Sweep/Cycle: 2 minutes Accelerated Speed: 20g Direction: X, Y,Z Duration: 4min ,4 times in each direction	IEC68-2-6 Vibration
3	Solderability	Temperature: 235±5℃ Time: 10±1 Sec	MIL-STD-202 Method 210B Condition B
4	Aging	Temperature: 100℃ Time:168 hours	MIL-STD-883H Method 1008.2
5	Fine Leak	Helium Bombing:0.4~0.5Mpa Time:1 hour	MIL-STD-883H METHOD 1014.13
6	High Temperature Storage	Temperature: 85℃ ± 5℃ Time 96 hours	IEC 60068-2-2
7	Temperature Cycle	Conditions: 25℃ ± 3℃ for 10 minutes -40℃ ± 3℃for 30 minutes 25℃ ± 3℃ for 10 minutes 125℃± 3℃ for 30 minutes 100 cycles	MIL-STD-883H METHOD 1010.8
8	Resistance to Soldering Heat	Pre-Heating:125℃ 60~120 Sec Solder temperature: 260± 5℃ Time: 20±5 sec	MIL-STD-202 Method 210B Condition B
9	Humidity	Temperature: 60℃ ± 2℃ Relative Humidity: 95% Time: 96 hours.	IEC 60068-2-3 Damp Heat
10	Thermal shock	-40℃ ± 3℃ to 100℃ ± 3℃, soak 15 minutes at each point, transfer time within 15 seconds, 20 cycles.	MIL-STD-883H METHOD 1011.9
11	Low Temperature Storage	Temperature: -40℃ ± 5℃ Time: 96 hours	IEC 60068-2-1
12	IR Reflow	Pre-Heating:150℃ to 200℃, 60-120 Sec Heating:217℃, 60 to 150 Sec Peak temp:260℃±5℃,20±5 Sec Times: 2 times	JEDEC J-STD-020C
13	Salt Spray	Temperature: 35±2℃ Salinity: 5% Time:24hrs	MIL-STD-883H Method 1009.8 Condition A

Rev	CREC's P/N	Cust P/N	Page
B0	01.X.UA.130JMVE0001843200	-	6

9 Product handling and control procedure

9.1 Precautions for storage

Storage of crystal units under higher temperature or high humidity for a long term may affects frequency stability or solderability. Please store the crystal units under the normal temperature and humidity without exposing to direct sunlight and dew condensation, and avoid the storage of crystal units for more than 6 months, and mount them as soon as possible after unpacking.

Item		Electrical Specification			
		Min.	Type	Max.	Unit
Storage peiod	After customer assembly	15		-	Year
	Crystal unused	-		2	Year

9.2 Mounting of SMD Type products

When using an automatic loading machine, please test and confirm to cause no damage to the crystal units before mounting. Bending the circuit board in the process of cleaving boards after mounting and soldering crystal units may cause peeling off the soldering or package cracks by mechanical stress.

9.3 Ultrasonic cleaning

General cleaning solutions or ultrasonic cleaning method may be used to clean CREC's products. However, under certain circumstances, ultrasonic cleaning machine could generate resonance at the oscillaton frequency of our products and thus deteriorate the electrical characteristics in devices, and even damage the overall structure of devices. Therefore, verification test is recommended before cleaning.

9.4 Ultrasonic welding

Avoid mounting and processing by Ultrasonic welding this method has a possibility of an excessive vibration spreading inside the crystal products and becoming the cause of characteristic deterioration and not oscillating. If Ultrasonic welding is being used in process, please notify us in advance to verify it.

Rev	CREC's P/N	Cust P/N	Page
B0	01.X.UA.130JMVE0001843200	-	7